

# AUTOTRONIK

Fertigungssysteme für die **Elektronikindustrie**

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## MODEL:

# SV350L

## IGBT Power Module Assembly Machine



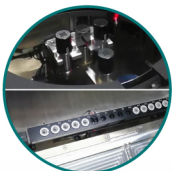
- ▶ Fully-Auto Assembly Process for IGBT Power Module
- ▶ Up to max. 2600uph (6 heads)
- ▶ Placement accuracy up to  $\pm 10\mu\text{m}$
- ▶ Multi feeding types system supportable
- ▶ Solder preform feeding (tape / tray form)
- ▶ Auto Nozzle Changer with max. 16 nozzles storage
- ▶ Auto Eject-pin Changer with heating system (option)
- ▶ Optional Dispensing System for glue / solder paste
- ▶ Optional Alcohol Spraying System for preform solder plate



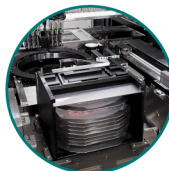
- 4 heads / 6 heads selectable
- Capacity up to 2200uph / 2600uph
- Placement accuracy : up to  $\pm 10\mu\text{m}$



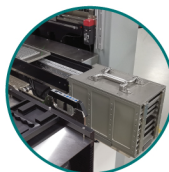
- Addition dispensing head and control system is optional
- For Glue / Solder paste dispensing process requirement
- Optional / customized features



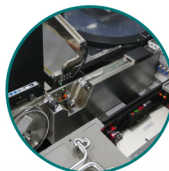
- Auto Eject-Pin Changer w/. 3 pin sets
- Auto Nozzle Changer with storage capacity as much as 16 nozzles
- Eject-pin heating system is option



- Auto Wafer Changer for max. 25 wafer flanges / cassette
- Support Wafer size from 8" / 6" /5" /4" and optional 12"



- QR-code scanning system for materials identification is optional
- Auto Tray Changer for max. 120mm\*120mm waffle tray \*16 pcs ( 2 pcs \* 8 carriers)
- Tray cassette capacity : 8 carriers



- Programmable for different materials on corresponding tray carrier / wafer flange
- Solder preform tape feeder for solder plate accurate cutting and feeding
- For preform size 2mm\*2mm to 30mm\*20mm



Innovative Features



Unbeatable Service



Worldwide for you!



Specialist in small and medium-sized manufacturing.



Quality & Innovation at a fair price.




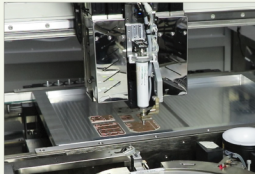
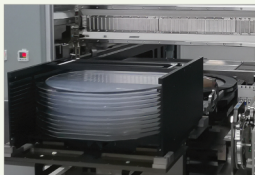
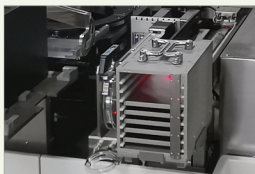

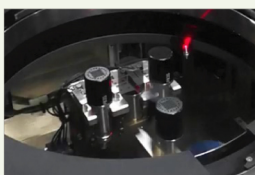
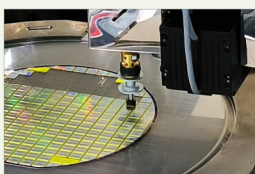
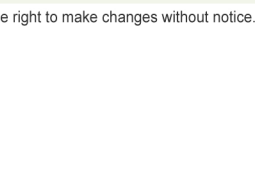
All from one hand.

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## SV350L

## IGBT Power Module Assembly Machine

Items	Specifications	Picture reference
XY Placement Accuracy	± 10 μm (θ ±0.3°)	
XY Resolution	0.001 mm / step	
Placement Heads	4 heads / 6 heads (pitch = 25mm)	
Placement Capacity (uph)	max. 2200 / max. 2600	
Dispensing System* (Option)	High precision dispensing system + Musashi ML-5000XII controller or High precision dispensing system + BCB KD-65 controller	
Conveyor System	Multiple segment with independent driver	
Size of Carrier	max. 460mm x 350mm x 20mm (Thickness = Carrier + Object)	
Conveyor Through	Left → Right	
Feeding Forms*	Wafer Flange, Tray Form, & Tape Feeder is available	
(1) Auto-Wafer Changer	Selectable 12" / 8" / 6" Wafer Die Flange auto-loading (12" is optional) for dies pickup area max. 200 x 200mm on flange 8" to 6" / 12" to 6" Wafer Flange Adapter is available (option) Flange Cassette capacity is max. 25pcs and support max. 25 types of wafer flange auto-loading and placement Wafer Die map-data is available to system programming	
(2) Auto-Tray Changer	Each Tray Cassette with 8 slots for tray carriers Size capacity up to 250mm x 120mm in each tray carrier , or two pieces of 120mm x 120mm waffle tray place on, and enough carrier clearance for max. 10mm height of component placing Support max. 8 types of (tray) components for auto-loading and placement	
(3) Tape Feeder Platform	max. 12 slots of 8mm Std. SMT tape feeder on the feeder platform, compatible with 8mm / 12mm / 16mm / 24mm Std. SMT tape feeder FD-20 / FD-30 type Solder-preform Tape Feeder is optional The corresponding specifications for solder-preform size is: (FD-20) W 2mm~20mm, L 0mm~20mm / (FD-30) W 2mm~30mm, L 0mm~20mm	
Size of Component (Die)	1mm x 1mm ~ 20mm x 20mm , Thickness : 0.06mm ~ 5.0mm	
Nozzle Changing Method	Auto-Nozzle-Changer for 16 Nozzles	
Jacking-Pin module	3 models selectable for chip size : 0.25~6 / 5~16 / 16~25 (mm)	
Eject-pin Set Changing Method*	By manual (Auto Eject-pin Changer is option)	
Alcohol Spraying	Optional alcohol spraying system with max. 3 nozzles at parallel	
Transmission control of X/Y	High precision linear motor driving system	
Qty of Camera	CCD camera x 2 sets	
FOV of bottom camera	20.7mm x 16.5mm (BT-CAM)	
FOV of Fid-CAM	20.7mm x 16.5mm (configuration of Fid-CAM & light source is depends on the flange material)	
Camera moving at Z-axis	Fid-CAM adopted auto-focus function with Z-axis movement	
Camera Calibration	System with camera centering auto-calibration function	
Fiducial Recognitions	Auto-positioning of holder, carrier-frame and fiducial	
Sequencing at Material PnP	Matrix Form (four orientations selectable)	
PCB Layout Conversion	CAD Conversion	
Operation System	Windows 10 ® (English / Chinese)	
Pressure Air Requirement	80 psi (5.5 bar) @ 150 Litre/min	
Power Supply Requirement	220VAC ± 10% , 50~60Hz , 3.8kW	
Dimension (L x W x H)	1400mm x 2000mm x 1800 mm (main unit without FFU)	
Weight (net)	approx. 2100 kg	

\* Customer must be confirmed the specification of feeding forms with seller before equipment purchase.

\*\* We reserve the right to make changes without notice.

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